



SOM-COMe-CT6- Dragonwing-IQ-X

COM Express 3.1 Type 6 Compact module with Dragonwing IQ-X Series processors in SiP-A, with Hexagon NPU, up to 45 TOPS

Performance & Efficiency: Dragonwing IQ-X Series-Powered Computing for Next-Gen Embedded Solutions



HIGHLIGHTS



CPU
Dragonwing IQ-X Series processors



CONNECTIVITY
1x NBase-T Ethernet port



NPU
Hexagon NPU, up to 45 TOPS



MEMORY
Up to 64GB LPDDR5 4224MT/s integrated on SiP

Available in Industrial Temperature Range



MAIN FIELDS OF APPLICATION



Healthcare
and Medical
devices



Smart cities



Retail



Digital Signage



Industrial PC

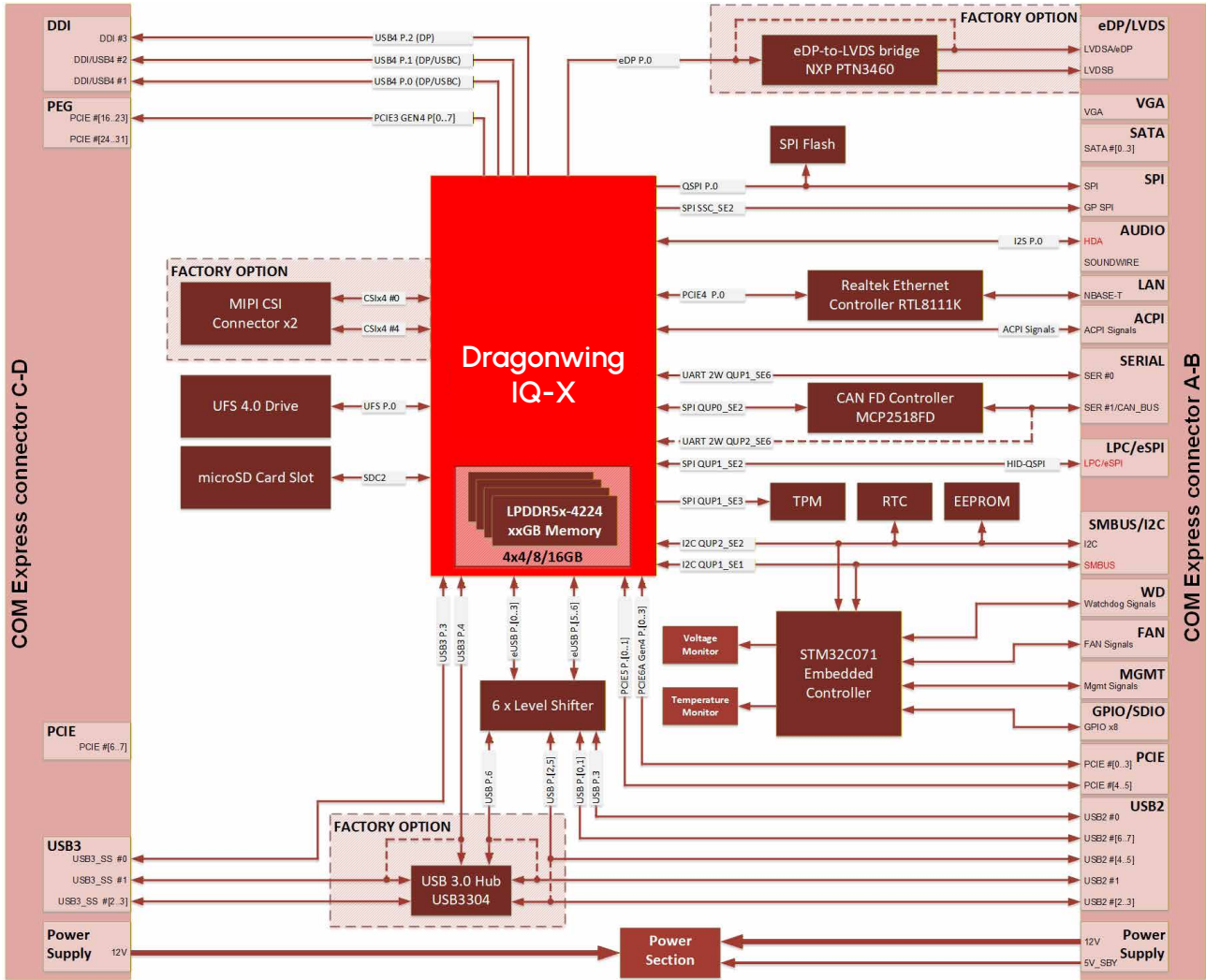
FEATURES

Processor	Dragonwing IQ-X Series processors in SiP-A <ul style="list-style-type: none"> • Dragonwing™ IQ-X7181MD, Custom Qualcomm Oryon™ 12-core CPU up to 3.4GHz • Dragonwing™ IQ-X5121MD, Custom Qualcomm Oryon™ 8-core CPU up to 3.4GHz 	USB	2x USB 10Gbps interfaces (without USB hub) 1x USB 10Gbps + 3xUSB 5Gbps (with USB hub) 8x Hi-Speed USB 2x USB4 Gen3x2 ports
NPU	Hexagon NPU, up to 45 TOPS	PCI-e	2x PCI-e x2 or 1x PCI-e x4 Gen4 port 1x PCI-e x2 Gen3 lport 1x PCI-e x8 Gen4 port on PEG pins
Memory	Up to 64GB LPDDR5 4224MT/s integrated on SiP	Audio	I2S audio interface on pins demanded to HD audio
Graphics	Qualcomm® Adreno™ GPU: <ul style="list-style-type: none"> • IQ-X7181MD: 1.25GHz GPU • IQ-X5121MD: 1.1GHz 	Serial Ports	Up to 2x 2-wires UARTs CAN port (optional)
Video Interfaces	Up to 4 independent displays 2x DP supporting DP / DP Alt Mode overType-C 1x DDI supporting DP 1x eDP or 1x LVDS Single/Dual Channel interfaces (factory alternatives)	Other Interfaces	Boot SPI General purpose SPI QSPI on LPC/eSPI 2x I2C Bus 4x GPIOs 4x GPOs Optional TPM 2.0 on-board
Video Resolution	DP: up to 5120x2880 @60Hz eDP up to 4K60Hz LVDS up to 1920x1200 @ 60Hz	Power Supply	+12V _{DC} ± 10%, +5V StandBy, +3.0V _{RTC}
Mass Storage	UFS 4.0 module on-board, optional, up to 1 TB microSD card slot I2C EEPROM	Operating System	Microsoft® Windows 11 IoT Enterprise Yocto Linux
Networking	1x NBase-T Ethernet port with Time-Sensitive Networking, supporting 10/100/1000/2500Mbps Realtek RTL8125 i RTL811k	Operating Temperature*	0° ÷ +60°C (Commercial Version) -40C ÷ +85°C (Industrial Version)
		Dimensions	95x95mm (COM Express Compact Form Factor)

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BLOCK DIAGRAM



Information subject to change. Please visit www.seco.seco.com to find the latest version of this datasheet

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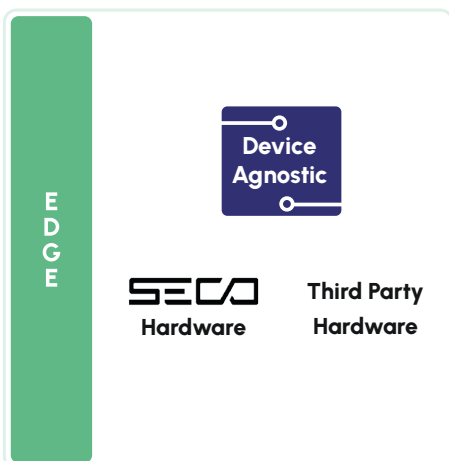
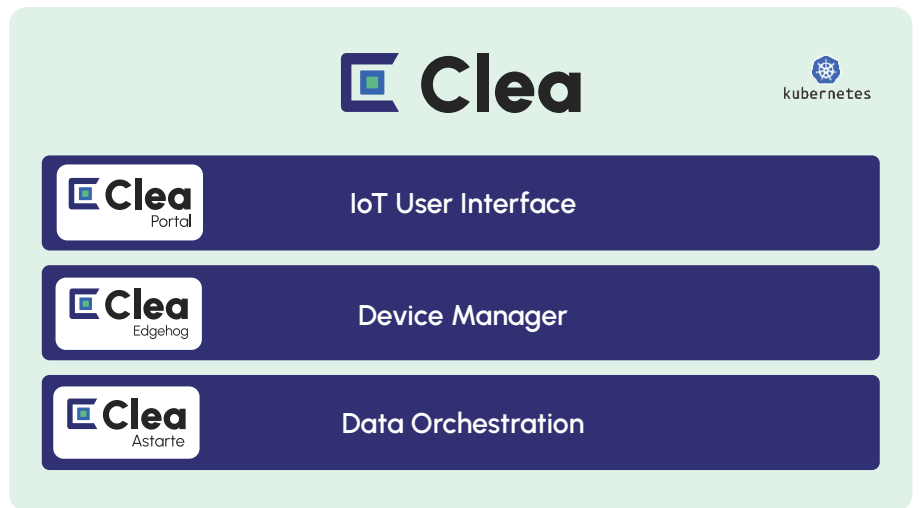
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